



N THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Moden et al.

Serial No.: 10/792,222

Filed: March 3, 2004

For: A METHOD FOR FORMING A LOW PROFILE MULTI-IC CHIP PACKAGE

CONNECTOR (as amended)

Confirmation No.: 4777

Examiner: M. Trinh

Group Art Unit: 3729

Attorney Docket No.: 2269-3389.8US

(97-0638.08/US)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

April 16, 2007 Date

> Leta M. Howard Name (Type/Print)

AMENDMENT UNDER 37 C.F.R. §1.116

Mail Stop AF Commissioner for Patents PO Box 1450 Alexandria, VA 22313-1450

Sir:

The following amendments and remarks are filed in response to the Examiner's remarks in the Final Office Action mailed February 28, 2007, the three-month shortened statutory period for response to which expires on May 28, 2007. This response is submitted on or before two months from the mailing date of the Final Office Action.

Amendments to the Specification begin on page 3 of this paper.

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